

L Number	Hits	Search Text	DB	Time stamp
1	113	(short adj circuit) with hillock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 10:30
2	42	(short adj circuit adj prevention) with (insulat\$ adj (film or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 12:02
3	77	("no" adj short adj circuit) with (insulat\$ adj (film or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 13:40
4	1	("no" adj short adj circuit) with (insulat\$ adj (film or layer)) with void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 12:04
5	63	void adj insulat\$ adj (film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 12:42
6	9	(void adj insulat\$ adj (film or layer)) and (short adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 12:41
7	283	((cavity or hole) adj insulat\$ adj (film or layer)) and (short adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 12:42
9	1249	((cavity or hole) adj insulat\$ adj (film or layer)) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 12:44
10	134	257/523.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 13:50
11	1347	257/622.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 14:00
12	792	257/623.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 14:00
-	2	4984200.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 06:18
-	1	4984200.pn. and (short adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 06:19
-	483	short adj circuit adj prevention	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 11:41

-	7	(short adj circuit adj prevention) and void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 06:26
-	1665	(short adj circuit) and void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 06:27
-	147	(short adj circuit) with void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 10:29